Abstract:

A device for unilateral etching of a semiconductor wafer (1) after the style of an etching cell, consisting of a base member (2) in the form of a plate with a central opening (4) which is smaller than the semiconductor wafer (1), and a lid (3) which closes the central opening (4) on one side of the base member (2) and is held releasably on the base member (2). The semiconductor wafer is adapted to be held on the base member (2) by means of a sealing arrangement (5) consisting of two elastic seals which are disposed in spaced relationship concentrically around the central opening (4) and between which a vacuum conduit (8) leads. The edge zone and back of the semiconductor wafer are protected from the attack of the etching medium if the sealing arrangement (5) is disposed on the side of the base member (2) facing the lid (3) and the lid (3), engaging over the sealing arrangement (5) and the semiconductor wafer (1) held thereon, is held releasably on the base member (2) with the interposition of another sealing arrangement (9).

To be published with Fig. 2

This Sheet Has Been Replaced

